LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC1747IFW#PBF **(Engineering Calculation)** TSSOP

TOTAL MASS (g): **0.179116**

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COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.005747**	**1000000**	**32085.36**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.065071	975000	363289.8
		Iron (Fe)	7439-89-6	0.001602	24000	8943.927
		Phosporus (P)	7723-14-0	2E-05	300	111.6595
		Zinc (Zn)	7440-66-6	4.7E-05	700	262.3999
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		**0.06674**	**1000000**	**372607.8**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.004600962	1000000	25687.06
		External Plating Total:		**0.004600962**	**1000000**	**25687.06**
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	0.0006	1000000	3349.785
		Internal Plating Total:		**0.0006**	**1000000**	**3349.785**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001428	750000	7972.489
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Resin (EP)		0.000476	250000	2657.496
		Die Attach Total:		**0.001904**	**1000000**	**10629.99**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.014777	150000	82499.63
		Bromine (Br)	40039-93-8	0.000985	10000	5499.231
		Silica (SiO2)	60676-86-0	0.079793	810000	445482.4
		Antimony Trioxide (Sb2O3)	1309-64-4	0.002955	30000	16497.69
		Metal Hydroxid		0	0	0
		Carbon Black (C)	1333-86-4	0	0	0
		Encapsulation Total:		**0.09851**	**1000000**	**549978.9**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.001014**	**1000000**	**5661.137**